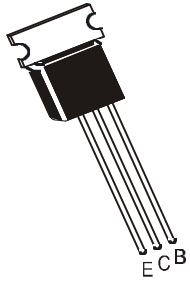


**PNP SILICON PLANAR EPITAXIAL TRANSISTORS**

**CSA683, CSA684**



**TO-237  
Plastic Package**

**Complementary CSC1383, CSC1384**

**AF Power Amplifier and Driver**

**ABSOLUTE MAXIMUM RATINGS(T<sub>a</sub>=25° C unless specified otherwise)**

DESCRIPTION	SYMBOL	CSA683	CSA684	UNIT
Collector -Base Voltage	V <sub>CBO</sub>	30	60	V
Collector -Emitter Voltage	V <sub>CEO</sub>	25	50	V
Emitter Base Voltage	V <sub>EBO</sub>	5.0		V
Collector Current Peak	I <sub>CP</sub>	1.5		A
Collector Current Continuous	I <sub>C</sub>	1.0		A
Collector Power Dissipation	*P <sub>C</sub>	1.0		W
Junction Temperature	T <sub>J</sub>	150		° C
Storage Temperature	T <sub>stg</sub>	- 55 to +150		° C

\*P<sub>C</sub>=750mW/Potting type: P<sub>C</sub>=750mW

**ELECTRICAL CHARACTERISTICS (T<sub>a</sub>=25° C unless specified otherwise)**

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Collector Cut off Current	I <sub>CBO</sub>	V <sub>CB</sub> =20V, I <sub>E</sub> =0			0.1	μA
Collector Emitter Voltage	V <sub>CEO</sub>	I <sub>C</sub> =2mA, I <sub>B</sub> =0	<b>CSA683</b>	25		V
			<b>CSA684</b>	50		V
Collector -Base Voltage	V <sub>CBO</sub>	I <sub>C</sub> =10μA, I <sub>E</sub> =0	<b>CSA683</b>	30		V
			<b>CSA684</b>	60		V
Emitter-Base Voltage	V <sub>EBO</sub>	I <sub>E</sub> =10μA, I <sub>C</sub> =0	5			V
DC Current Gain	*h <sub>FE</sub>	I <sub>C</sub> =500mA, V <sub>CE</sub> =10V	85		340	
		I <sub>C</sub> =1A, V <sub>CE</sub> =5V	50			
Collector Emitter Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =500mA, I <sub>B</sub> =50mA			0.4	V
Base Emitter Saturation Voltage	V <sub>BE(sat)</sub>	I <sub>C</sub> =500mA, I <sub>B</sub> =50mA			1.2	V
Transition Frequency	f <sub>T</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =50mA		200		MHz
Output Capacitance	C <sub>ob</sub>	V <sub>CB</sub> =10V, I <sub>E</sub> =0, f=1MHz			30	pF

\*h<sub>FE</sub> Classifications

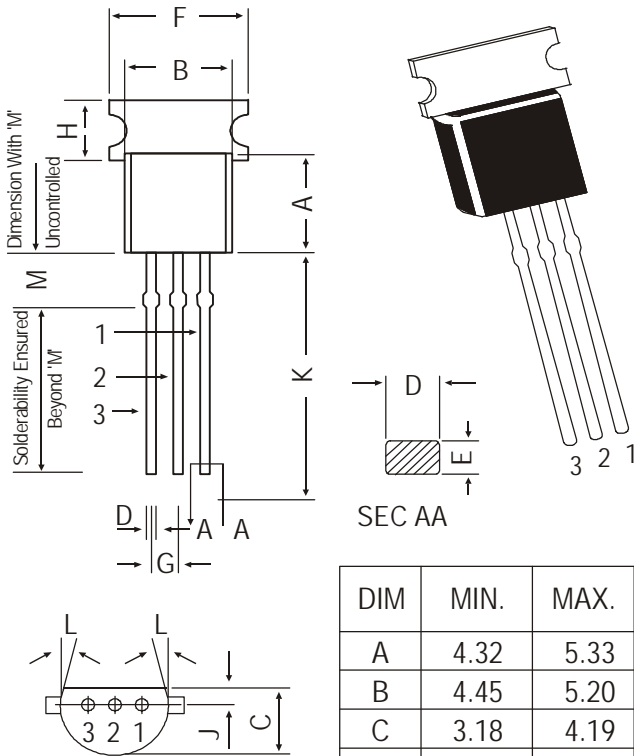
**Q : 85 - 170**

**R : 120 - 240**

**S : 170 - 340**

**TO-237  
Plastic Package**

**TO-237 Plastic Package**

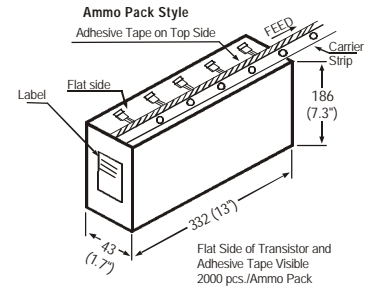
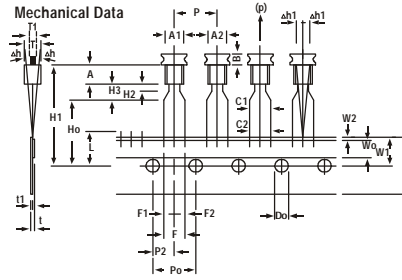


All dimensions in mm.

DIM	MIN.	MAX.
A	4.32	5.33
B	4.45	5.20
C	3.18	4.19
D	0.41	0.55
F	—	5.40
G	1.14	1.40
H	—	2.54
K	12.70	—
L	5 DEG	
J	1.14	1.53
M	1.982	2.082

**PIN CONFIGURATION**

1. BASE
2. COLLECTOR
3. EMITTER



All dimensions in mm

ITEM	SYMBOL	SPECIFICATION			
		MIN.	NOM.	MAX.	TOL.
BODY WIDTH	A1	4.0		4.8	
BODY HEIGHT	A	4.8		5.2	
BODY THICKNESS	T	3.9		4.2	
PITCH OF COMPONENT	P		12.7		± 1
*1 FEED HOLE PITCH	Po		12.7		± 0.3
FEED HOLE CENTRE TO COMPONENT CENTRE	P2		6.35		± 0.4
DISTANCE BETWEEN OUTER LEADS	F		5.08		+0.6 -0.2
*3 COMPONENT ALIGNMENT SIDE VIEW	Δh		0	1.0	
*4 COMPONENT ALIGNMENT FRONT VIEW	Δh1		0	1.3	
TAPE WIDTH	W		18		± 0.5
HOLD-DOWN TAPE WIDTH	W0		6		± 0.2
HOLE POSITION	W1		9		+0.7 -0.5
HOLD-DOWN TAPE POSITION	W2		0.5		± 0.2
LEAD WIRE CLINCH HEIGHT	Ho		16		± 0.5
COMPONENT HEIGHT	H1			32.25	
LENGTH OF SNIPPED LEADS	L			11.0	
FEED HOLE DIAMETER	Do		4		± 0.2
*5 TOTAL TAPE THICKNESS	t			1.2	
LEAD - TO - LEAD DISTANCE	F1, F2		2.54		+0.4 -0.1
STAND OFF	H2	0.45		1.45	
CLINCH HEIGHT	H3			3.0	
LEAD PARALLELISM	C1 - C2			0.22	
PULL - OUT FORCE	(P)		6N		
HEAT SINK WIDTH	A2			5.40	
HEAT SINK HEIGHT	B			2.54	
HEAT SINK THICKNESS	T1			0.45	

**NOTES**

1. Maximum alignment deviation between leads will not be greater than 0.2mm.
2. Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.
3. Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.
4. There will be no more than three (3) consecutive missing components in a tape.
5. A tape trailer, having at least three feed holes is provided after the last component in a tape.
6. Splices should not interfere with the sprocket feed holes.

**REMARKS**

- \*1 CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH    \*2 TO BE MEASURED AT BOTTOM OF CLINCH  
\*3 AT TOP OF BODY    \*4 AT TOP OF BODY    \*5 t1 0.3-0.6

**Packing Detail**

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-237 Bulk	1K/polybag	240 gm/1K pcs	3" x 7.5" x 7.5"	5K	17" x 15" x 13.5"	80K	26.2 kgs
TO-237 T&A	2K/ammo box	725 gm/2K pcs	12.5" x 8" x 1.8"	2K	17" x 15" x 13.5"	32K	13.8 kgs

### **Disclaimer**

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